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(54) HIGH FREQUENCY MULTILAYER WIRING
SUBSTRATE AND ITS PRODUCTION

(57) Abstract:

PROBLEM TO BE SOLVED: To produce a high frequency multilayer wiring substrate which can easily form its internal high frequency transmission line of an NRD guide structure.

SOLUTION: This multilayer wiring substrate 1 includes an insulating substrate 3 where the insulating layers 2 consisting of plural low dielectric substances are laminated, and the conductor layers formed on the surfaces of substrates 3 and/or among layers 2. Then every layer 2 has a through-groove where a high dielectric substance is buried and is held between the upper and lower conductor layers. Thus, a transmission line consists of a high dielectric substance part 4 which is buried in the line direction of the layer 2 with width L_1 and a pair of conductor layers 5 and 6 which are formed on the upper and lower surfaces of the part 4 with width L_2 larger than the width L_1 respectively.

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